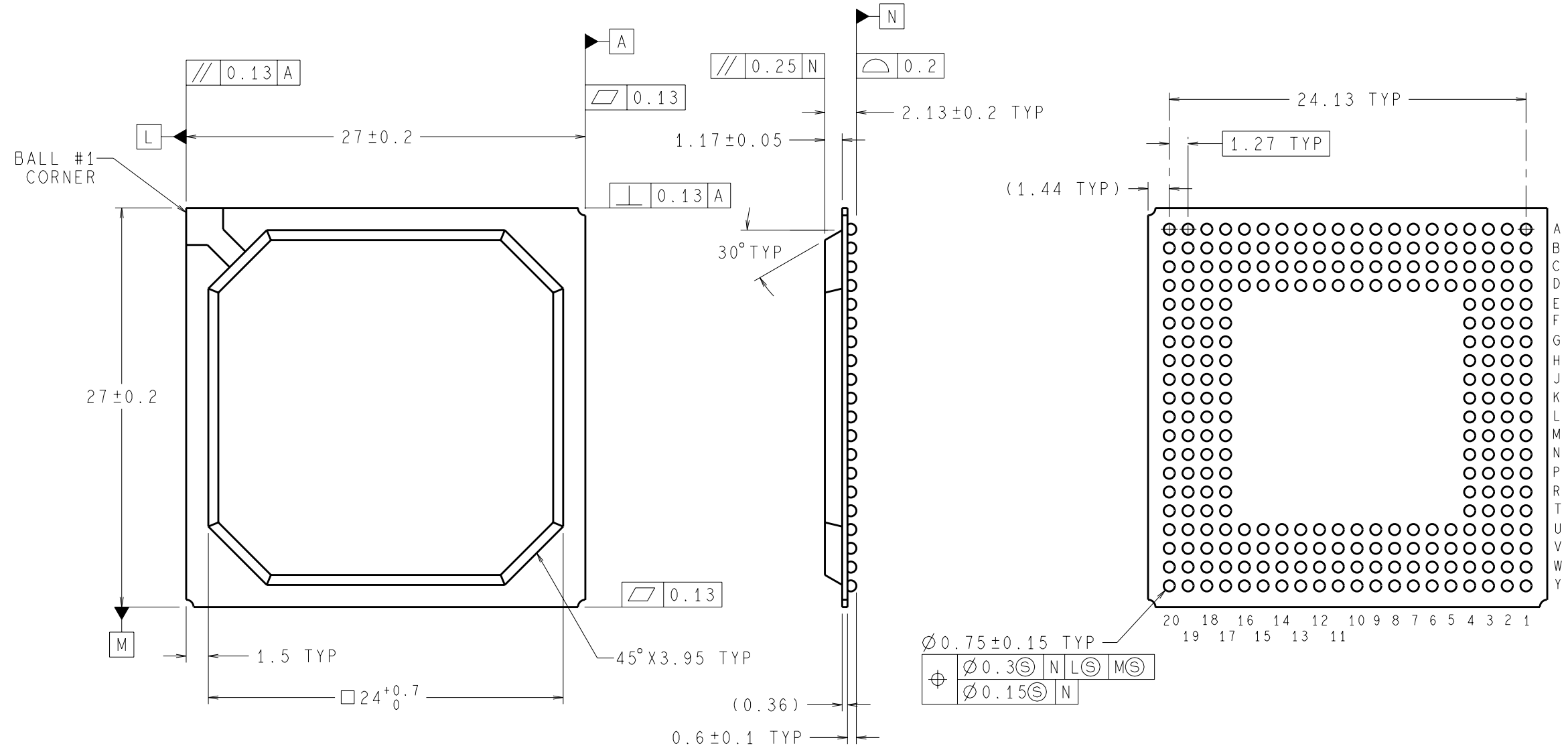


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL.	10591	10/19/94	DEG/SL
B	TITLE 27 X27 WAS 35 X 35.	10751	01/10/95	DEG/SL
C	DELETE (S) FROM TITLE, UPDATE NOTE 2, UPDATE GEOM. TOL. PER CURRENT STDS.	12228	06/29/1999	MS/MJL
D	REVISE GEOM TOL'S; BALL $\varnothing 0.75 \pm 0.15$ WAS $0.76 \pm 0.05$ ; DIM $2.13 \pm 0.2$ WAS $2.13 + 0.17 / - 0.13$ ; DIM $1.17 \pm 0.05$ WAS $1.17 + 0.08 / - 0.02$ ; DIM $(0.36)$ WAS $0.36 \pm 0.05$ ; REVISE NOTE 2.	219	12/07/2000	MS/AP



DIMENSIONS ARE IN MILLIMETERS

- NOTES: UNLESS OTHERWISE SPECIFIED
- SOLDER BALL COMPOSITION: Sn 63%, Pb 37%.
  - REFERENCE JEDEC REGISTRATION MO-151, VARIATION BAL-2.

APPROVALS		DATE		 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN <b>D.E. Grady</b>		05/17/1995			
DFTG. CHK. THANH LEQUANG		12/07/2000		<b>PBGA,</b> <b>27 X 27 X 2.13mm,</b> <b>256 BALL, 1.27mm PITCH</b>	
ENGR. CHK. ANINDYA PODDAR		12/07/2000			
 PROJECTION INCH [MM]		SCALE N/A	SIZE C	DRAWING NUMBER (SC)MKT-UBB256A	REV D
DO NOT SCALE DRAWING				SHEET 1 of 1	